US00D929534S

(12) **United States Design Patent** (10) **Patent No.: US D929,534 S**
Amano et al. (45) **Date of Patent: ** *Aug. 31, 2021**

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(54) **LIQUID DISCHARGE NOZZLE FOR SEMICONDUCTOR SUBSTRATE PROCESSING APPARATUS**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **15 Years**

(21) Appl. No.: **29/710,426**

(22) Filed: **Oct. 23, 2019**

(30) **Foreign Application Priority Data**

Apr. 25, 2019 (JP) 2019-009324

(51) **LOC (13) Cl.** **23-01**
(52) **U.S. Cl.**
USPC **D23/213**; D23/259
(58) **Field of Classification Search**
USPC D23/213, 214, 215, 223, 224, 226, 229, D23/230, 249, 259, 262; D15/135
CPC A61H 9/0021; A61H 33/00; B05B 1/00; B05B 1/14; B05B 1/185; B05B 1/08; B05B 1/02; B05B 1/26; B05B 12/002; B05B 1/18; B05B 9/01
See application file for complete search history.

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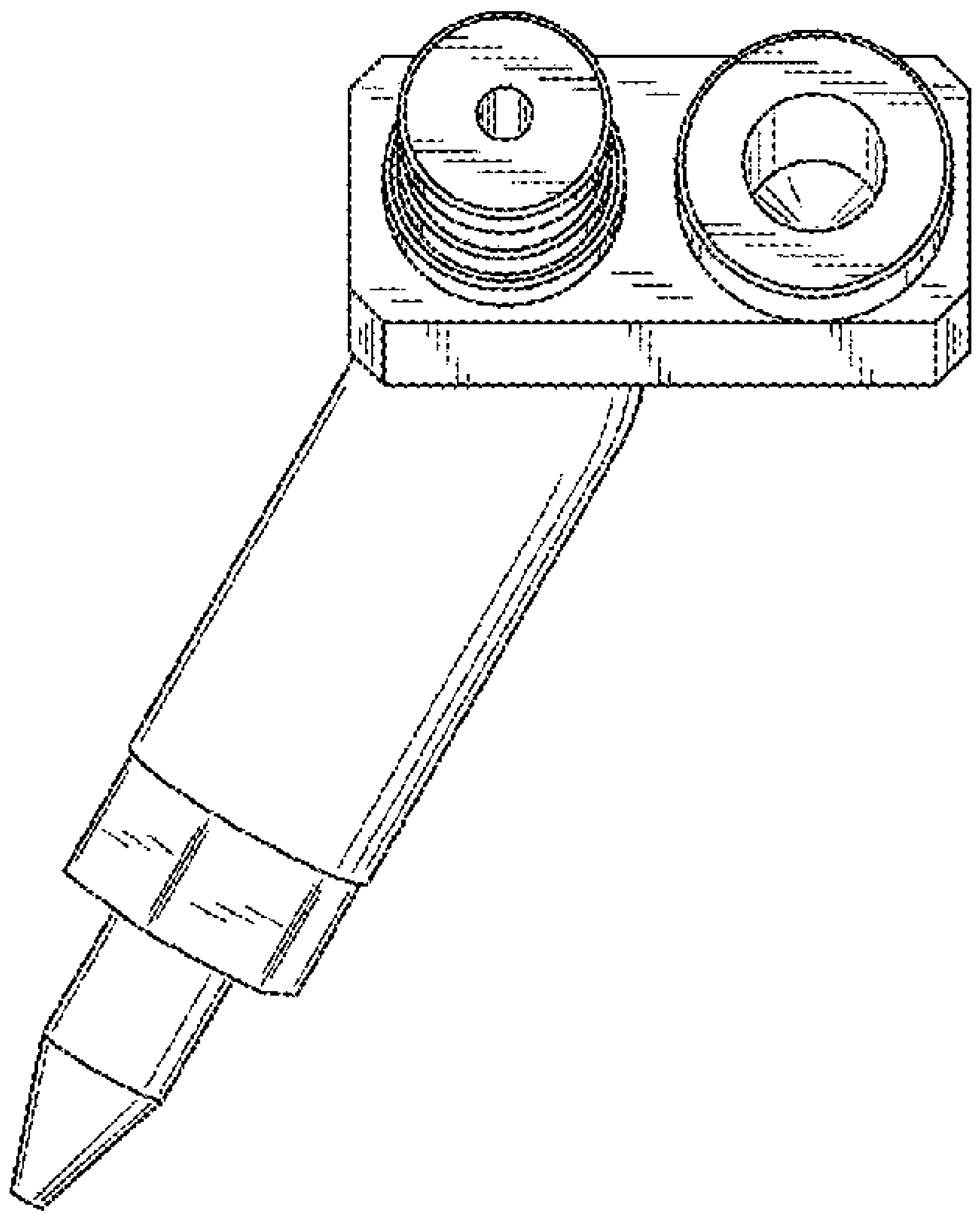
(57) **CLAIM**

The ornamental design for a liquid discharge nozzle for semiconductor substrate processing apparatus, as shown and described herein.

DESCRIPTION

FIG. **1** a front, top perspective view of a liquid discharge nozzle for semiconductor substrate processing apparatus;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left-side elevational view thereof;
FIG. **5** is a right-side elevational view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.

1 Claim, 7 Drawing Sheets



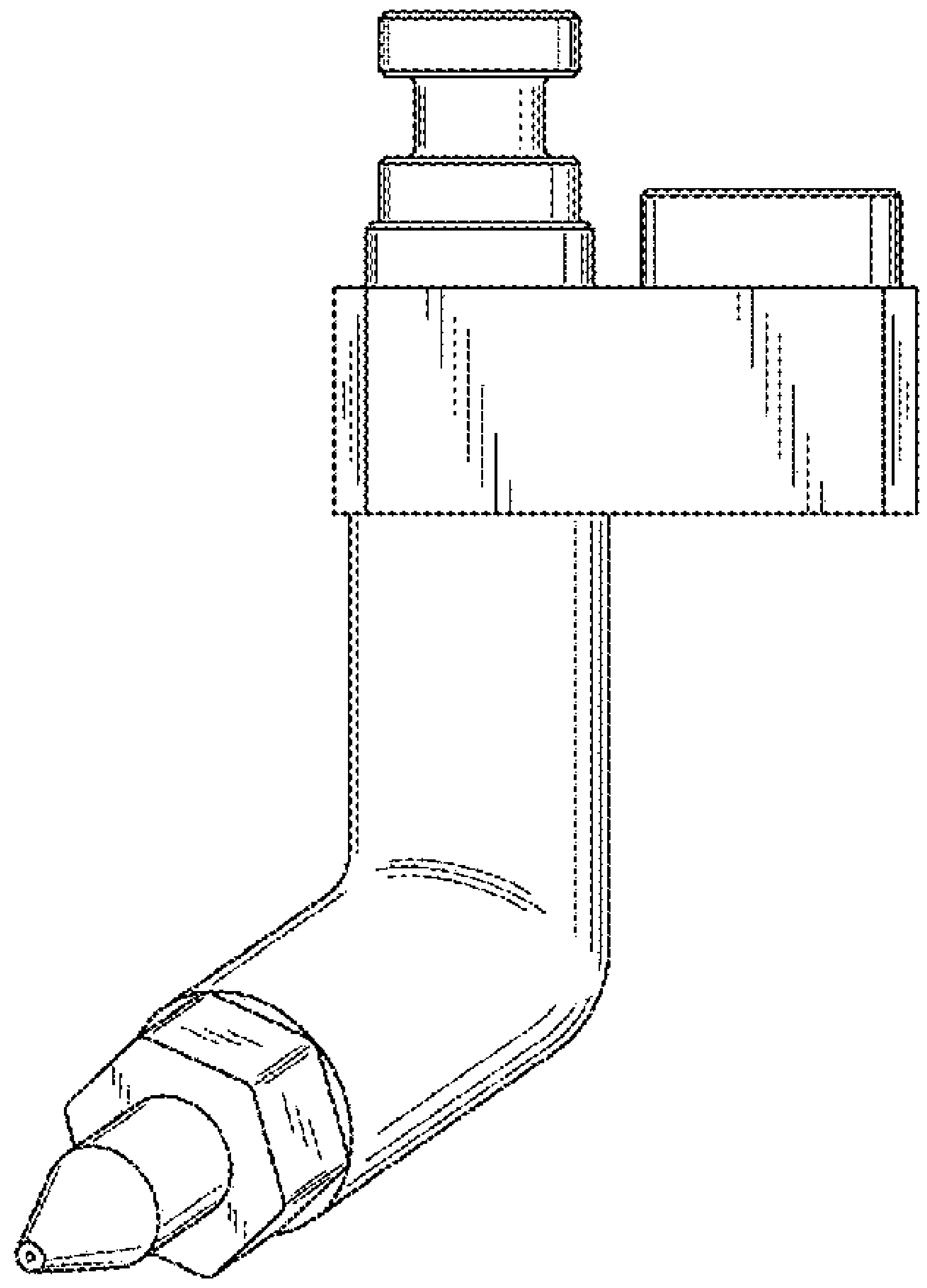


FIG. 1

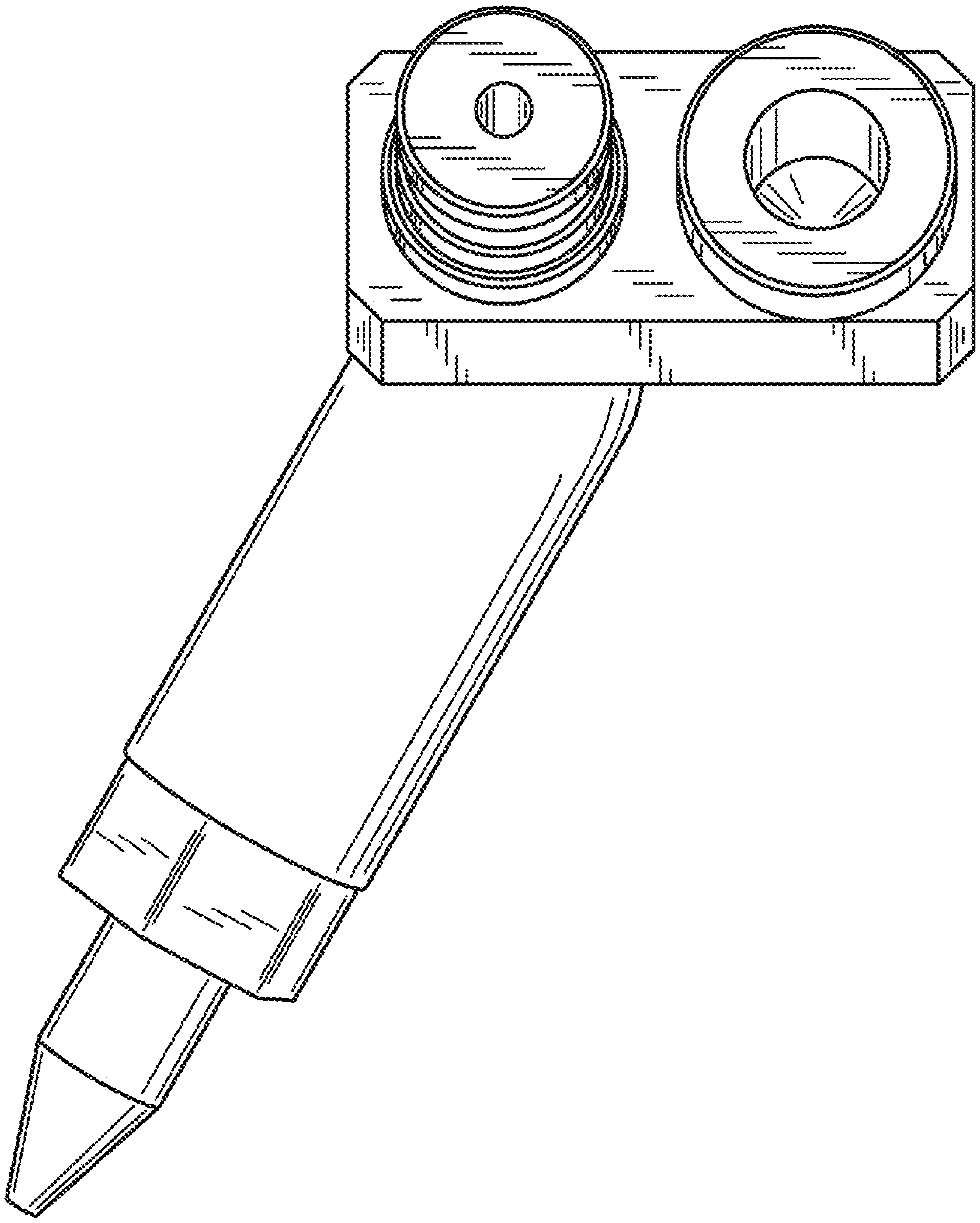


FIG. 2

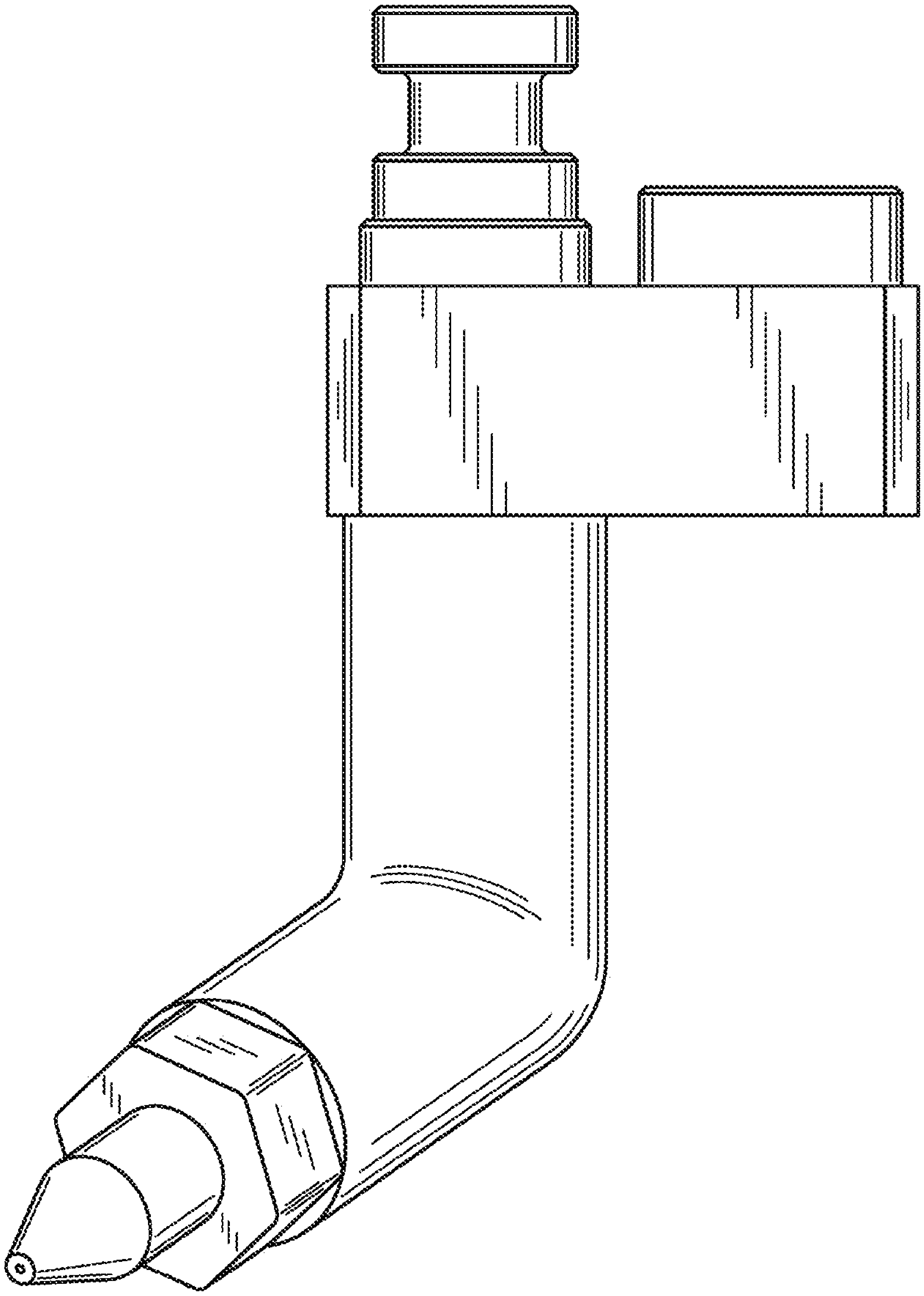


FIG. 3

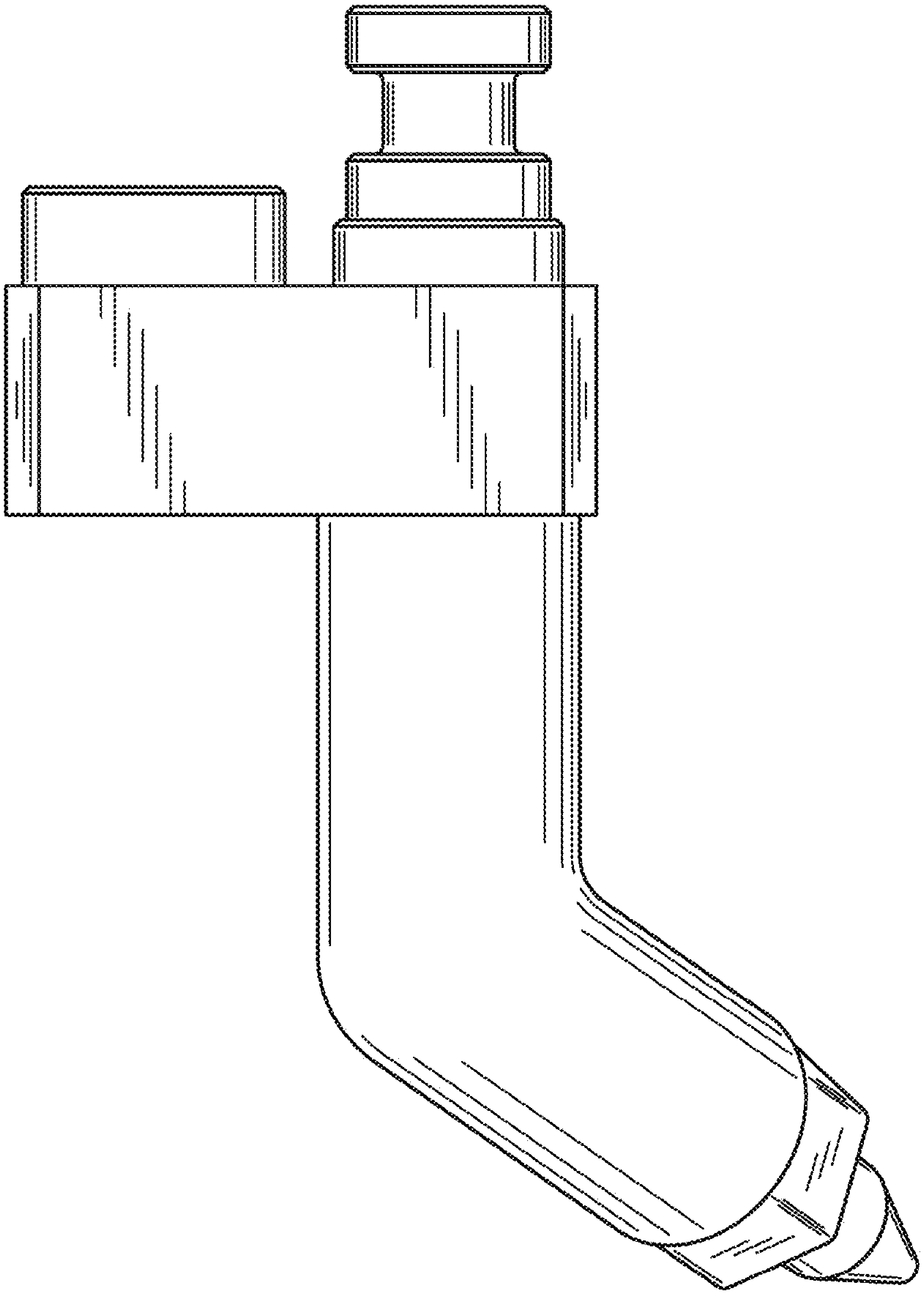


FIG. 4

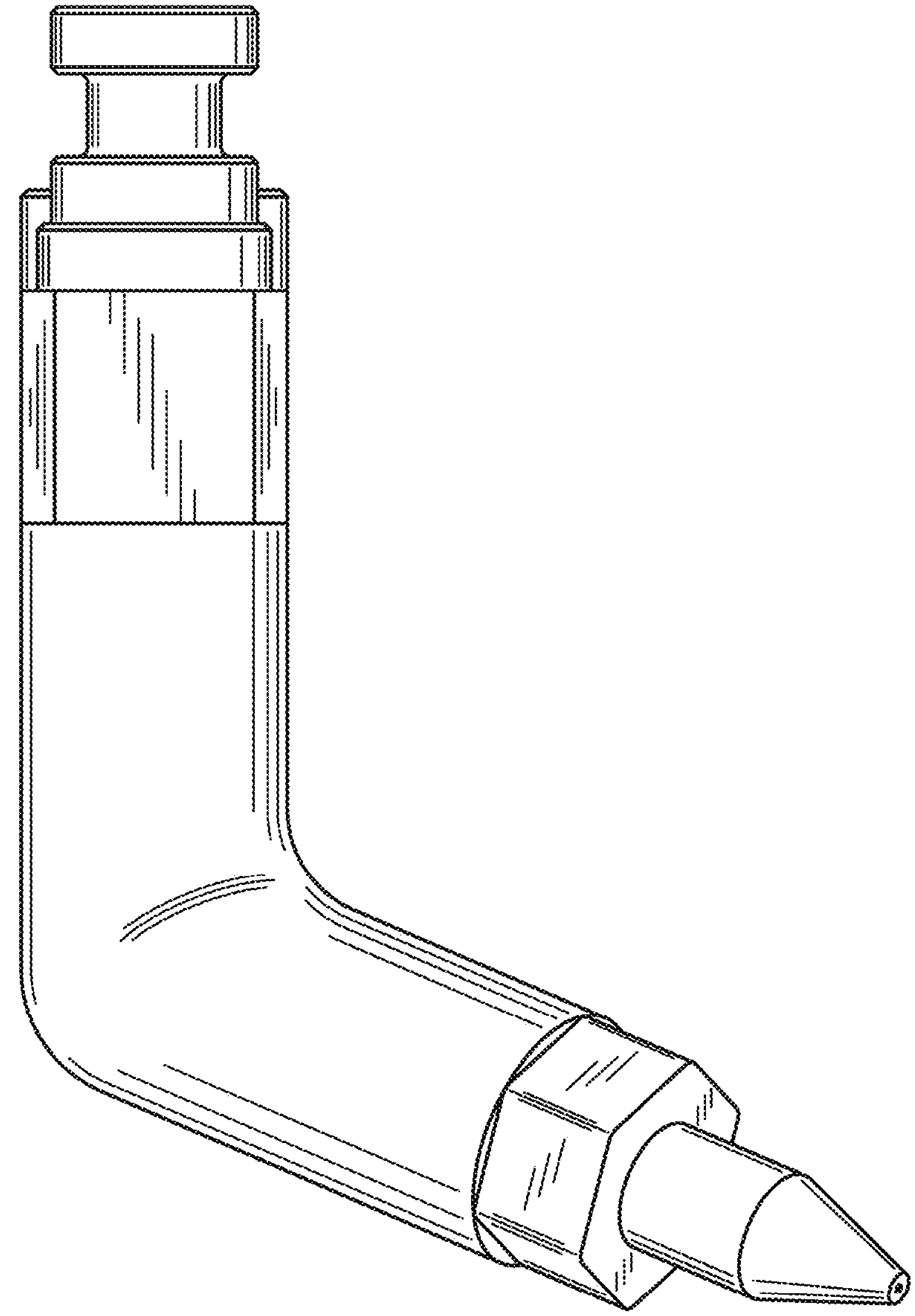


FIG. 5

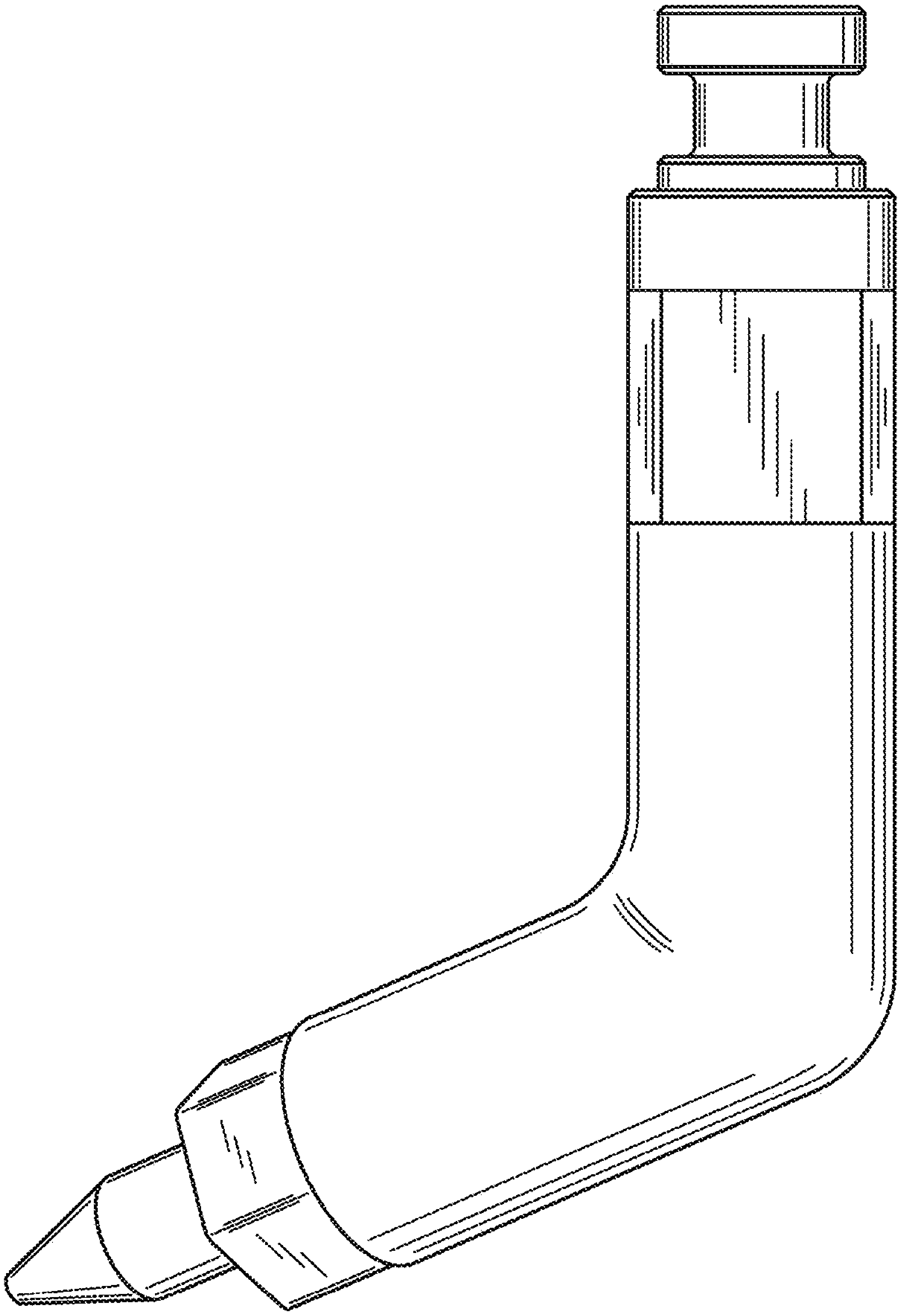


FIG. 6

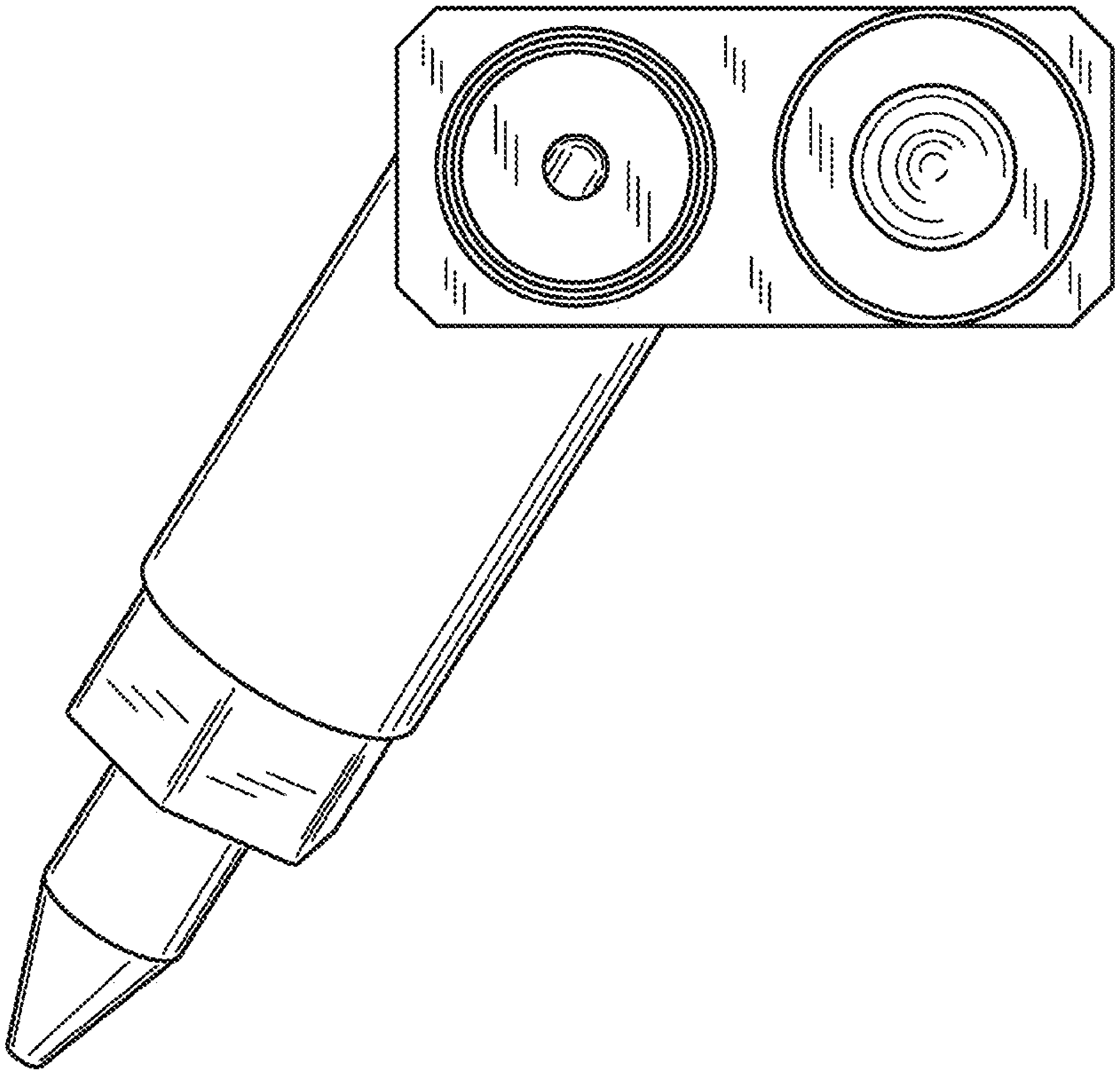


FIG. 7